

### **Description**

The MT5033 devices provide a power supply solution for products powered by either a one-cell Li-lon or Li-polymer battery. The converter generates a stable output voltage that is either adjusted by an external resistor divider or fixed internally on the chip. It provides high efficient power conversion and is capable of delivering output currents up to 2.5A at 5V at a supply voltage down to 3V. The maximum peak current in the step-up switch is limited to a value of 6A. The MT5033 operates at 800kHz switching frequency and enters pulse-skip-mode (PSM) operation at light load currents to maintain high efficiency over the entire load current range. During shutdown, the load is completely disconnected from the battery.

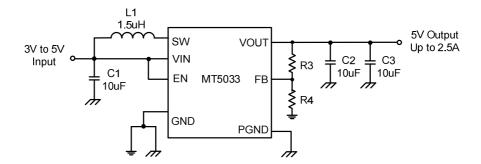
#### **Features**

- Synchronous Step-up Converter with 2.5A
  Output Current From 3V Input
- Wide VIN Range From 2.9V to 5.5V
- Input Under-voltage Lockout Protection
- Fixed and Adjustable Output Voltage
- Built-in Output Over-voltage Protection
- Light-Load Pulse Skip Mode
- Load Disconnect During Shutdown
- Output Short Circuit Protection
- Thermal Shutdown Protection
- Pb-Free(ROHS compliant)
- Available in a SOP8\_EP Packages

#### **Applications**

- Power Bank
- USB Charging Port (5V)
- DC/DC Micro Modules

#### **Typical Application**



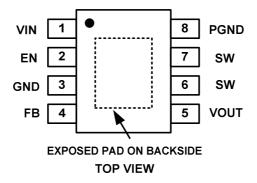


# **Ordering Information**

Part No.	Marking	Temp. Range	Package	Remark	MOQ
MT5033NSPR	MT5033 YWWXX	-40℃ ~+85℃	SOP8L_EP		2500/Tape & Reel

Note: Y:Year, WW:Week, XX:Control Code

# **Pin Configuration**



### **Pin Description**

The Booth Phone						
NAME	PIN NO.	DESCRIPTION				
VIN	1	Input Supply voltage				
EN	2	Enable input. (1/VIN enabled, 0/GND disabled)				
GND	3	Analog Ground pin. Connect GND to PGND under EP.				
FB	4	Voltage feedback of adjustable versions. Connect FB to GND and set fixed 5.15V output voltage.				
VOUT	5	Step-up convert output				
SW	6, 7	Step-up and rectifying switch input				
PGND	8	Power Ground pin.				
EP		Exposed pad must be soldered to achieve appropriate power dissipation. Connect EP to GND.				



### Absolute Maximum Rating (Reference to GND) (Note1)

Supply Voltage $V_{\text{IN}}$ to GND0.3V to 6V	Junction temperature range 150℃
Output Voltage V <sub>OUT</sub> 0.3V to 6V	Storage temperature range55℃ to 150℃
$V_{\text{EN}},V_{\text{FB}},V_{\text{SW}}$ to GND0.3V to 6V	Lead Temperature260℃
Peak Output Current Internal Limited	ESD Classification

#### Recommended Operating Conditions (Note2)

Input Voltage V <sub>IN</sub>	2.9V to 5.5V	Ambient Temperature Range40℃	c to 85℃
Output Voltage Vout	2.9V to 5.5V	Junction temperature range	135℃

#### Thermal Information (Note3,4)

Maximum Power Dissipation (T <sub>A</sub> =25 $^{\circ}$ C) 2.15W	Thermal resistance θ <sub>JA</sub> 51℃/M
	Thermal resistance θ <sub>10</sub>

Note1: Stress exceeding those listed "Absolute Maximum Ratings" may damage the device.

Note2: The device is not guaranteed to function outside of the recommended operating conditions.

Note3: Measured on JESD51-7, 4-Layer PCB.

Note4: The maximum allowable power dissipation is a function of the maximum junction temperature  $T_{J\_MAX}$ , the junction to ambient thermal resistance  $\theta_{JA}$ , and the ambient temperature  $T_A$ . The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $P_{D\_MAX} = (T_{J\_MAX} - T_A)/\theta_{JA}$ . Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.

#### **Electrical Characteristics**

Unless otherwise noted, all parameter limits are established over the recommended operating conditions:

 $\underline{T_{\text{A}}} = 25 \text{°C}, \ 2.9 \text{V} \leq V_{\text{IN}} \leq 5.5 \text{V}, \ \text{unless otherwise noted}. \ \text{Typical values are at V}_{\text{IN}} = V_{\text{EN}} = 3.6 \text{V} \ \text{and} \ V_{\text{OUT}} = 5 \text{V}.$ 

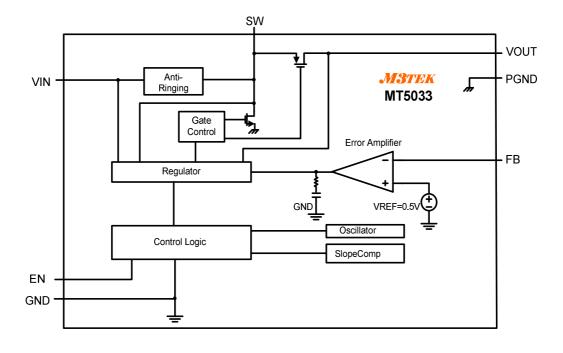
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input voltage range V <sub>IN</sub>		2.5		5.5	V
Input Under-voltage Lockout			2.2		V
Threshold V <sub>UVLO</sub>					
Output voltage adjustable		0.5			\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
range V <sub>OUT</sub>		2.5		5.5	V
Fixed Output Voltage	FB=GND	4.95	5.15	5.25	V
Feedback voltage V <sub>FB</sub>		490	500	510	mV
Oscillator frequency fosc		640	800	960	kHz
NCH Switch Current Limit	V <sub>OUT</sub> = 5V		6		А
NCH Switch on resistance	V <sub>OUT</sub> = 5V		50		mΩ



## **Electrical Characteristics (continued)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
PCH Switch on resistance		V <sub>OUT</sub> = 5V		50		mΩ
Shutdown Current		$V_{EN} = 0V, V_{IN} = 3.6V$		0.1	1	μΑ
Quiescent Current V <sub>IN</sub>		V <sub>FB</sub> =0.55V , Vout=5V		125	200	μΑ
EN logic low voltage					0.4	V
EN logic high voltage			1.4			V
EN leakage current		Clamped on GND or V <sub>IN</sub>	-1		1	μΑ
Thermal Shutdown				150		°C
Thermal Shutdown Hyst	teresis			20		°C

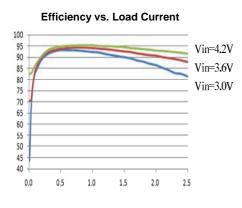
## **Functional Block Diagram**

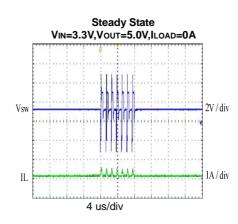


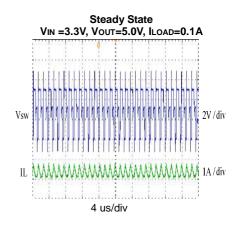


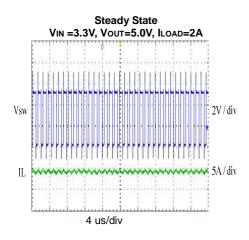
### **Typical Performance Characteristics**

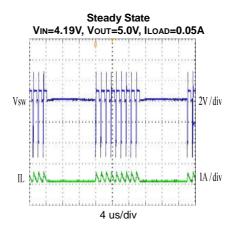
V<sub>IN</sub> = 3.3V, MT5033 typical application circuit (Figure 1.), TA = +25℃, unless otherwise noted.

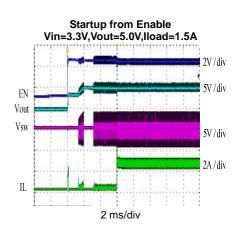


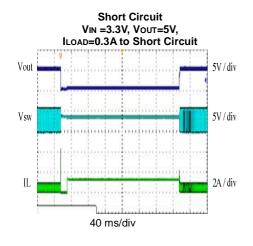


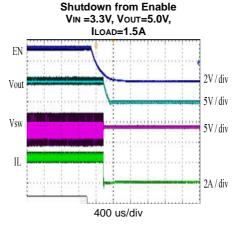


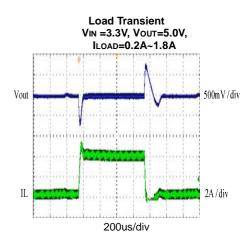














#### **Detailed Description**

The MT5033 is based on a fixed frequency current mode pulse width modulation topology. The peak current of the NMOS switch is sensed to limit the maximum current flowing through the switch and the inductor. The typical peak current limit is set to 6A. An internal temperature sensor prevents the device from getting overheated in case of excessive power dissipation.

#### **Application Information**

Because of the high integration of MT5033, the application circuit is simple. Only input capacitor CIN, output capacitor COUT, inductor L, output feedback resistors R3, R4 need to be selected for the targeted applications specifications.

#### **Setting the Output Voltage**

The MT5033output voltage can be adjusted with an external resistor divider (See Figure 1). The typical value of the voltage on the FB pin is 500mV. The maximum allowed value for the output voltage is 5.5 V. Choose the bottom resistor R4 in the  $100\text{k}\Omega\sim500\text{k}\Omega$  range to set the divider current at 1  $\mu\text{A}$  or higher. The value of resistor R3, depending on the needed output voltage  $V_{\text{OUT}}$ , can be calculated using:

$$R_3 = R_4 \times \left( \frac{V_{OUT}}{V_{FB}} - 1 \right) = 200 \, K\Omega \times \left( \frac{V_{OUT}}{500 \, mV} - 1 \right)$$

#### **Inductor Selection**

The MT5030A 800 kHz high switching frequency allows for the use of small surface mount inductors. For high efficiency, choose inductors with high frequency core material, such as ferrite, to reduce core losses. Also to improve efficiency, choose inductors with bigger size for a given inductance. The inductor should have low DCR (copper-wire resistance) to reduce  $I^2R$  losses, and must be able to handle the peak inductor current without saturating. The inductor DC current rating should be greater than the maximum input average current. For the full 2Amp output current applications, the inductor shall have enough core volume to support peak inductor currents in the 4A to 7A range and DCR less than  $10m\Omega$ . The highest peak current through the inductor and the switch depends on the output load, converter efficiency  $\eta$ , the input voltage ( $V_{BAT}$ ), and the output voltage ( $V_{OUT}$ ). Estimation of the maximum average inductor current can be done using:

$$I_{L} = I_{OUT} \times \frac{V_{OUT}}{V_{BAT} \times \eta}$$

A good estimation for the inductor ripple current is 20% to 40% of the output current.

$$\Delta I_{L} = (20\% \sim 40\%) \times I_{OUT (MAX)} \times \frac{V_{OUT}}{V_{IN}}$$

$$L = \frac{V_{IN} \times (V_{OUT} - V_{IN})}{\Delta I_{I} \times F_{SW} \times V_{OUT}}$$

For example, for an output current of 2A at 5V with 85% efficiency, at least 4.7A of average current flows through the inductor at a minimum input voltage of 2.9V.

The MT5030 step-up converters can operate with an effective inductance in the range of  $1\mu$ H to  $2.2\mu$ H and with output capacitors in the range of  $20\mu$ F to  $100\mu$ F. The internal compensation is optimized for an output filter of L =  $1.5\mu$ H and  $C_{OUT} = 20\mu$ F. To minimize radiated noise, use a toroidal or shielded inductor.



#### Input Capacitor

Place at least a 10  $\mu$ F input ceramic capacitor close to the IC is to improve transient behavior of the regulator and EMI behavior of the total power supply circuit.

#### **Output Capacitor**

The output capacitor must completely supply the load during the charging phase of the inductor. A reasonable value of the output capacitance depends on the speed of the load transients and the load current during the load change. It is recommended to use X7R ceramic capacitors placed as close as possible to the VOUT and PGND pins of the IC. A recommended output capacitance value is around 20~100µF. Note that high capacitance ceramic capacitors have a DC Bias effect, which will have a strong influence on the final effective capacitance. A 10 V rated 0805 capacitor with 10µF can have an effective capacitance of less 5µF at an output voltage of 5V.

The first step to calculate the switch current is to determine the duty cycle D for the minimum input voltage. The minimum input voltage is used because this leads to the maximum switch current.

#### Thermal information

Implementation of integrated circuits in low-profile and fine-pitch surface-mount packages typically requires special attention to power dissipation. Many system-dependent issues such as thermal coupling, airflow, added heat sinks and convection surfaces, and the presence of other heat-generating components affect the power-dissipation limits of a given component.

Three basic approaches for enhancing thermal performance are listed below:

- High speed switching path (SW, PGND and VOUT with wide PCB traces) must be kept as short as possible.
- Solder the exposed pad of the MT5030A to the ground plane with multiple big thermal vias.
- Choose a bigger size 1.5uH Inductor with the lowest DCR value for given PCB space

The maximum junction temperature ( $T_J$ ) of the MT5033 devices is 125°C. The thermal resistance of the SOP8\_EP package is  $R_{\theta JA} = 38.2$ °C/W, if the Exposed PAD is soldered. Specified regulator operation is assured to a maximum ambient temperature  $T_A$  of +50°C. Therefore, the maximum power dissipation for the SOP8\_EP package it is about 1.96W. More power can be dissipated if the maximum ambient temperature of the application is lower.

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{R_{\theta JA}} = \frac{125 \text{ °C} - 50 \text{ °C}}{38.2 \text{ °C} / W} = 1.96 \text{ W}$$

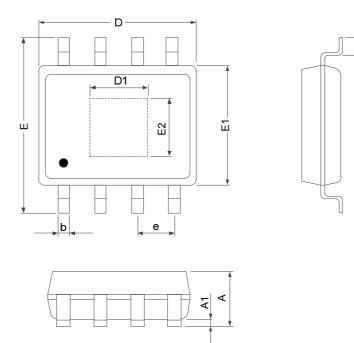
#### Layout consideration

Use wide and short traces for the main current path and for the power ground tracks. The input capacitor, output capacitor, and the inductor should be placed as close as possible to the IC. Use a common ground node for power ground and a different one for analog ground to minimize the effects of ground noise. Connect these ground nodes at any place close to the ground pins of the IC.



### **PACKAGING INFORMATION**

## SOP\_8L (EP) PACKAGE OUTLINE DIMENSONS

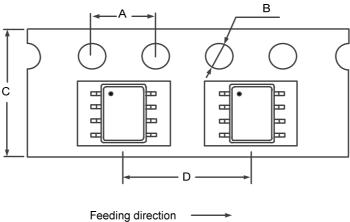


SYMBOLS	MILLIMETERS		INCHES			
STIVIBULS	MIN.	MAX.	MIN.	MIN.		
А	1.35	1.75	0.053	0.069		
A1	0.00	0.25	0.000	0.010		
D	4.9	90	0.1	0.193		
E1	3.9	90	0.153			
D1	3.3	30	0.130			
E2	2.4	40	0.095			
Е	5.80	6.20	0.228	0.244		
L	0.40	1.27	0.016	0.050		
b	0.31	0.51	0.012	0.020		
е	1.2	27	0.0	50		

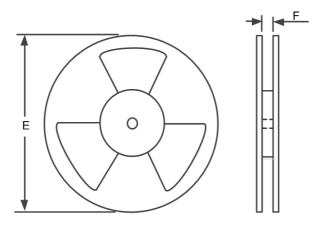


## **Carrier Tape & Reel Dimensions**

#### 1. Orientation / Carrier Tape Information :



#### 2. Rokreel Information:



#### 3. Dimension Details:

PKG Type	А	В	С	D	E	F	Q'ty/Reel
SOP 8L 150 mils	4.0 mm	1.5 mm	12.0 mm	8.0 mm	13 inches	13.0 mm	2,500



#### **Reflow Profile**

#### **Classification of Reflow Profile**

Reflow Profile	Green Assembly
Average Ramp-Up Rate (Ts <sub>min</sub> to Tp)	1~2°C/second
Preheat	
-Temperature Min(Ts <sub>min</sub> )	150°C
-Temperature Max(Ts <sub>max</sub> )	200°C
-Time(ts <sub>min</sub> to ts ts <sub>max</sub> )	60~180 seconds
Time maintained above:	217°C
-Temperature(T <sub>L</sub> )	40~50 seconds
-Time(t <sub>∟</sub> )	40~30 Seconds
Peak Temperature(Tp)	250 +0/-5 °C
Time within 5°C of actual Peak Temperature(tp)	15 seconds max.
Ramp-Down Rate	3°C/second
Time 25°C to Peak Temperature	8 minutes max.

Note: For all temperature information, please refer to topside of the package, measured on the package body surface.

